SCBS158E - JANUARY 1991 - REVISED MAY 1997

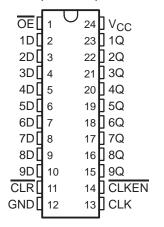
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- Buffered Control Inputs to Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (NT) and Ceramic (JT) DIPs

description

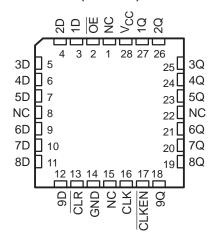
These 9-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

With the clock-enable (CLKEN) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock. Taking CLKEN high disables the clock buffer, thus latching the outputs. Taking the clear (CLR) input low causes the nine Q outputs to go low, independently of the clock.

SN54ABT823...JT OR W PACKAGE SN74ABT823...DB, DW, OR NT PACKAGE (TOP VIEW)



SN54ABT823 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

A buffered output-enable (\overline{OE}) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT823 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT823 is characterized for operation from -40° C to 85° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



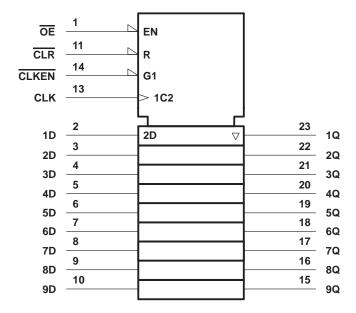
SN54ABT823, SN74ABT823 9-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCBS158E - JANUARY 1991 - REVISED MAY 1997

FUNCTION TABLE (each flip-flop)

	OUTPUT				
OE	CLR	CLKEN	CLK	D	Q
L	L	Х	Χ	Χ	L
L	Н	L	\uparrow	Н	Н
L	Н	L	\uparrow	L	L
L	Н	Н	Χ	Χ	Q ₀
Н	Χ	X	Χ	Χ	Z

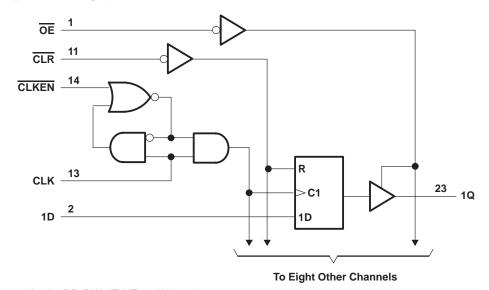
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and W packages.



logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} — — —	0.5 V to 7 V
Input voltage range, V _I (see Note 1) –	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT823	96 mA
SN74ABT823	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stg}	°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SN54ABT823, SN74ABT823 9-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCBS158E - JANUARY 1991 - REVISED MAY 1997

recommended operating conditions (see Note 3)

		SN54ABT823		SN74A	UNIT	
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
loн	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		5		5	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Т	T _A = 25°C			BT823	SN74ABT823		UNIT
PARAMETER	TEST CON	DITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	0.55 ±1 ±50 ±100 50 -180 250 38 250 1.5	UNII
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
	V _{CC} = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/o	V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Vo	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V
VOL	vCC = 4.5 v	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V_{hys}				100						mV
lį	V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ
l _{OZPU} ‡	$V_{CC} = 0 \text{ to } 2.1 \text{ V, } V_{O} = 0.9$	5 V to 2.7 V, OE = X			±50		±50		±50	μА
lozpd [‡]	$V_{CC} = 2.1 \text{ V to } 0, V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{OE} = X$				±50		±50		±50	μΑ
IOZH	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$				10§		10§		10§	μΑ
lozL	V _{CC} = 2.1 V to 5.5 V, V _O	= 0.5 V, OE ≥ 2 V			-10§		-10§		-10§	μΑ
I _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50		50		50	μΑ
ΙΟ [¶]	V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-140	-180	-50	-180	-50	-180	mA
	5577	Outputs high		1	250		250		250	μА
ICC	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		24	38		38		38	mA
	1 00	Outputs disabled		0.5	250		250		250	μΑ
ΔI _{CC} #	V _{CC} = 5.5 V, One input at Other inputs at V _{CC} or GN				1.5		1.5		1.5	mA
C _i	V _I = 2.5 V or 0.5 V			4						pF
Co	V _O = 2.5 V or 0.5 V			7						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] This data sheet limit may vary among suppliers.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

SCBS158E - JANUARY 1991 - REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} = 5 V, T _A = 25°C		SN54ABT823		SN74ABT823		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	125	0	125	0	125	MHz
		CLR low	5.5		5.5		5.5		
t _W I	Pulse duration	CLK high	2.9		2.9		2.9		ns
		CLK low	3.8		3.8		3.8	2.9 r 3.8 2.5 2.1	
		CLR inactive	2.5		2.5		2.5		
١.	Setup time before CLK↑	Data	2.1		2.1		2.1]
t _{su}	Setup time before CLK	CLKEN high	2	2 2		2			
		CLKEN low	3.3		3.3		3.3		
		Data	1.3		1.3		1.3		
th	Hold time after CLK↑	CLKEN high	1		1		1		ns
		CLKEN low	2		2		2		

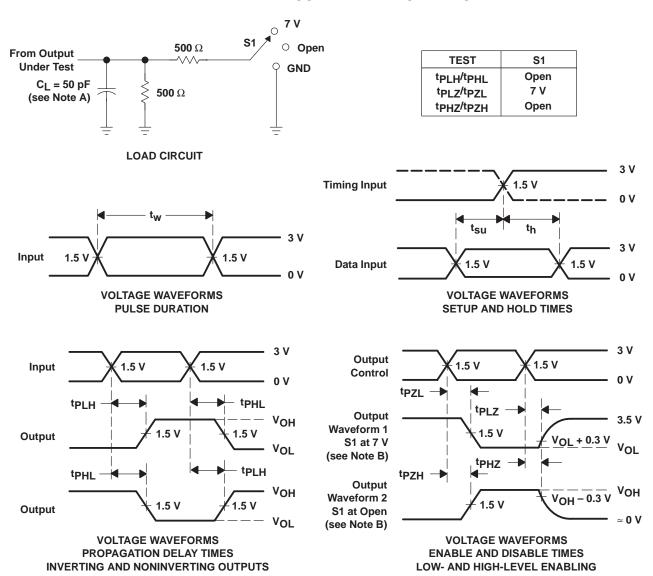
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C	<u>',</u>	SN54A	BT823	SN74A	BT823	UNIT	
	(INPOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	AX MIN MAX 125 MHz 8.1 2.1 6.8 7 2.2 6.7 7.3 2 7.1 ns 6.3 1 6† 6.6 2.2 6.5† NAME UNIT			
f _{max}			125	200		125		125		MHz	
t _{PLH}	CLK	Q	2.1	4.3	5.9	2.1	8.1	2.1	6.8	ne	
^t PHL		α	2.2	4.4	6.1	2.2	7	2.2	6.7	115	
t _{PHL}	CLR	Q	2	4.1	6.3	2	7.3	2	7.1	ns	
^t PZH	ŌĒ	Q	1	3	4.7†	1	6.3	1	6†	no	
tPZL		α	2.2	4.1	5.6	2.2	6.6	2.2	6.5	110	
^t PHZ	ŌĒ	tPHZ 05	Q	2.7	4.8	6.5†	2.7	7.7	2.7	7.5†	ns
t _{PLZ}	OE .	ζ	1.9	5	6.4	1.9	7.4	1.9	6.9	115	

[†]This data sheet limit may vary among suppliers.

SCBS158E - JANUARY 1991 - REVISED MAY 1997

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated